

# QUALCOMM® SNAPDRAGON™ WEAR

# 1100

## WEARABLES PROCESSOR

### The Wearables Processor for Targeted Purpose Devices

**The Snapdragon Wear 1100 is designed for targeted purpose wearables:**

- + Compact 79mm<sup>2</sup> size including MDM, PMIC and WTR, in 28nm LP
- + Integrated Next Gen 4G LTE CAT 1 multimode modem with Power Save Mode (PSM)
- + Integrated voice support for CSFB and VoLTE
- + Integrated Qualcomm® iZat™ Gen 8C GNSS
- + ARM Cortex A7 CPU
- + Pre-integrated support for Qualcomm® Vive™ Wi-Fi/Bluetooth, featuring Qualcomm® MU | EFX MU-MIMO
- + Software support Linux and RTOS
- + Multiple ODM designs available

To learn more visit:

[snapdragon.com](http://snapdragon.com) or [qualcomm.com/wearables](http://qualcomm.com/wearables)

## USER EXPERIENCES



### 45% Smaller\*

Compact package allows for highly optimized wearable designs



### Low Power

Low power design allows up to 7-days of LTE standby†, for longer battery life



### Always connected

Next-gen 4G LTE CAT 1 multi-mode modem, with integrated GNSS



### Smart Sensing

Integrated low power sensor hub enabling richer algorithms and greater accuracy



### Secure Location

Combining robust security with Qualcomm iZat Gen 8c GNSS for trusted location tracking



### Snapdragon Wear Platform

A common package for both connected and tethered designs, multiple ODM partners, help accelerate development and reduce cost

Qualcomm®  
snapdragon 

\* As compared to Qualcomm QSC6270.

† When paired with a typical, 350 mAh battery.

Qualcomm Snapdragon is a product of Qualcomm Technologies, Inc. Qualcomm iZat, Qualcomm MU|EFX, and Qualcomm Vive are products of Qualcomm Atheros, Inc.



Snapdragon Wear 1100 provides a low-power, GNSS and LTE enabled processor for smart tracker and targeted purpose wearables

## FEATURES & SPECIFICATIONS

### CPU

- + Integrated Applications Processor with ARM Cortex A7 at 1.2 GHz with 256KB L2 cache

### Memory

- + Support for discreet or MCP NAND and LPDDR2

### Display

- + Support for simple UI and displays

### Cost-Optimized

- + Integrated features designed to reduce Bill-of-Materials (BOM) and NRE for customers including an ARM Cortex A7 eliminating the need for MCUs, GNSS for location services, and scalable software re-use across chipset platform

### Power Management

- + Ultra-low Rock Bottom Sleep Current (RBSC) for extended standby
- + Power Save Mode (PSM)

### Modem

- + Integrated 4G CAT 1 LTE Global Mode modem, supporting LTE FDD, LTE TDD, TD-SCDMA and GSM
- + Up to 10 Mbps downlink and 5Mbps uplink with LTE multi-mode and LTE single mode capability with dual and single Rx support
- + Integrated voice support for Circuit Switch Fall Back (CSFB) and VoLTE
- + Core modem with proven and trusted technology already deployed across hundreds of millions of devices worldwide

### Location

- + iZat Gen 8C location technology
- + GPS, GLONASS, Galileo, and BeiDou constellations supported
- + Pinpoint location, even in challenging urban environments

### Scalable

- + Broad software re-use to reduce design complexity, BOM, and NRE
- + Scalability to add voice, Wi-Fi, and Bluetooth capabilities

### Connectivity

- + Pre-integrated support to add VIVE Wi-Fi (1x1, 802.11ac) featuring Qualcomm MUJEFX MU-MIMO technology and Bluetooth 4.1/Bluetooth Low Energy

### Charging

- + Companion charging chipset

### Security

- + Hardware based security with Secure Boot/storage/debug, hardware crypto engine, hardware random number generator, and Trustzone

